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(54) **PRETREATMENT PROCESS FOR ELECTROLESS PLATING OF RESIN MOLDED BODY, METHOD FOR PLATING RESIN MOLDED BODY, AND PRETREATMENT AGENT**

(57) The present invention provides a pretreatment process for electroless plating of a resin molded article, comprising etching the resin molded article using a manganate salt-containing etching solution, and then bringing the resin molded article into contact with an aqueous solution containing a reducing compound and an inorganic acid; and a plating process of a resin molded article comprising the pretreatment process. Further, the

present invention provides various treatment agents for use in the plating process. According to the present invention, a plating layer with sufficient adhesion can be formed when an etching treatment is performed using a manganate salt-containing etching solution in an electroless plating treatment of a resin molded article.

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